

LAYERED SUPPORT AND METHOD FOR LAMINATING CMP PADS

ABSTRACT OF THE DISCLOSURE

A device and method for laminating CMP pads includes supporting the CMP pad with a board having material compositions similar to the CMP pad. By thus supporting the CMP pad during lamination, there is less likelihood of damage to the CMP pad and better adhesion from lamination. In particular, the CMP pad materials are laminated while in contact with a first board that may have a recess to accept the CMP pad. The pad has dimensions that are equal to or greater than the pad material. In an alternative embodiment, a board is provided on the opposite side of the CMP pad for lamination.